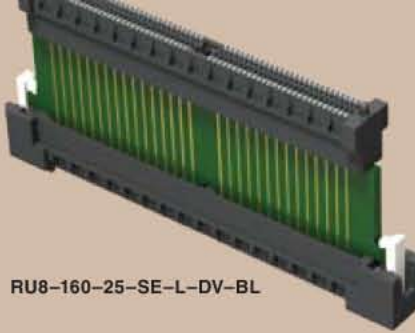


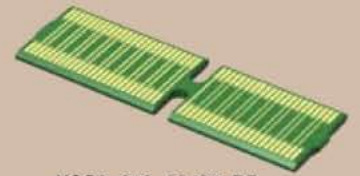


(0,80mm) .0315"

RU8, HSC8 SERIES



RU8-160-25-SE-L-DV-BL



HSC8-050-02-25-DP



• Board lock option

HIGH SPEED RISER CARD KIT

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?RU8

Connector:

Insulator Material: Black LCP

Contact: BeCu

Plating: Au or Sn over 50µ" (1,27µm) Ni

Current Rating: 3.1A @ 30°C

Temperature Rise (See website for details)

Operating Temp: -55°C to +125°C

Processing: Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10mm) .004" max (40-60)

RoHS Compliant: Yes



Protocols Supported

PCI Express®
XAUI, SATA

Download app notes at
www.samtec.com/appnote
Contact SIG @ samtec.com
for questions on protocols

| RU8 | 1 | POSITIONS PER ROW | STACK HEIGHT | SIGNAL ROUTING | PLATING OPTION | DV | BL | OTHER OPTION |
|-----|---|-------------------|--|---|---|----|---|---|
| | | 40, 50, 60 | -19 = (19mm) .748" -25 = (25mm) .984" -30 = (30mm) 1.180" | -SE = Single-Ended -DP = Differential Pair | -L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail (Plating for connectors) Plating for Card is Hard Gold | | -BL = Board Locks (Bottom Socket only) (Not available on -19 stack height) | Leave blank for Trays -K = (5,50mm) .217" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel |

Note: Some lengths, styles and options are non-standard, non-returnable.

Note: Other Gold plating options available. Contact Samtec.

| NO. OF POSITIONS PER SIDE | A | B | -SE TOTAL SIGNAL LINES | -DP TOTAL SIGNAL PAIRS |
|---------------------------|---------------|---------------|------------------------|------------------------|
| 40 | (39,80) 1.567 | (50,39) 1.984 | 40 | 26 |
| 50 | (47,80) 1.882 | (58,39) 2.299 | 50 | 32 |
| 60 | (55,80) 2.197 | (66,40) 2.614 | 60 | 38 |

| RU8 25mm Stack Height | Rated @ 3dB Insertion Loss* |
|-----------------------------|-----------------------------|
| Single-Ended Signaling | 7.5 GHz / 15 Gbps |
| Differential Pair Signaling | 7.5 GHz / 15 Gbps |

*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at www.samtec.com?RU8 or contact sig@samtec.com

Mates with: HSEC8

SPECIFICATIONS

For complete specifications see www.samtec.com?RU8

Conductor: 1/2 oz Copper

Contact Area: Hard Gold Plated

Insulator: FR-4

RoHS Compliant: Yes

| NO. OF POSITIONS PER SIDE | -SE TOTAL SIGNAL LINES | -DP TOTAL SIGNAL PAIRS |
|---------------------------|------------------------|------------------------|
| -040 | 40 | 26 |
| -050 | 50 | 32 |
| -060 | 60 | 38 |

Note: Some sizes, styles and options are non-standard, non-returnable.

| HSC8 | NUMBER OF POSITIONS PER SIDE | CARD STYLE | STACK HEIGHT | SIGNAL ROUTING |
|------|------------------------------|------------------------------------|--|---|
| | -040, -050, -060 | -02 = (1,60mm) .062" thick card | -19 = (19mm) .748" -25 = (25mm) .984" -30 = (30mm) 1.180" | -SE = Single-Ended -DP = Differential Pair |

| STACK HEIGHT | A |
|--------------|---------------|
| -19 | (14,84) .584 |
| -25 | (20,84) .820 |
| -30 | (25,84) 1.017 |

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Samtec:](#)

[HSC8-060-02-19-SE](#) [RU8-140-30-DP-L-DV-BL](#)